

# N-Channel Super Junction Power MOSFET $\, \mathrm{I\!V}$

#### **General Description**

The series of devices use advanced trench gate super junction technology and design to provide excellent RDS(ON) with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

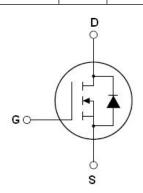
#### **Features**

- Optimized body diode reverse recovery performance
- ●Low on-resistance and low conduction losses
- Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ROHS compliant

#### **Application**

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)
- LLC Half-bridge

V <sub>DS min@Tjmax</sub>	710	V
R <sub>DS(ON)TYP</sub>	460	mΩ
ID	8	Α
Qg	12.8	nC



Schematic diagram

## **Package Marking And Ordering Information**

Device	Device Package	Marking
NCE65N520F	TO-220F-3L	NCE65N520F



TO-220F

Table 1. Absolute Maximum Ratings (T<sub>C</sub>=25℃)

Parameter	Symbol	Value	Unit	
Drain-Source Voltage (VGS=0V)	V <sub>DS</sub>	650	V	
Gate-Source Voltage (VDS=0V) AC (f>1 Hz)	Vgs	±30	V	
Gate-Source Voltage (VDS=0V) DC	Vgs	±20	V	
Continuous Drain Current at Tc=25°C	I <sub>D (DC)</sub>	8	А	
Continuous Drain Current at Tc=100°C	I <sub>D (DC)</sub>	5.6	А	
Pulsed drain current (Note 1)	I <sub>DM (pluse)</sub>	24	Α	
Maximum Power Dissipation(Tc=25°C)	P <sub>D</sub>	31.6	W	
Derate above 25°C		0.21	W/°C	
Avalanche current <sup>(Note 2)</sup>	I <sub>AS</sub>	2.5	А	
Drain Source voltage slope, V <sub>DS</sub> ≤480 V,	dv/dt	50	V/ns	
Reverse diode dv/dt, V <sub>DS</sub> ≤480 V,I <sub>SD</sub> <i<sub>D</i<sub>	dv/dt	15	V/ns	
Operating Junction and Storage Temperature Range	T <sub>J</sub> ,T <sub>STG</sub>	-55+175	°C	

<sup>\*</sup> limited by maximum junction temperature



## Table 2. Thermal Characteristic

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R <sub>thJC</sub>	4.74	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R <sub>thJA</sub>	62	°C /W

 Table 3. Electrical Characteristics (TA=25℃unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states	<u>'</u>			•	•	
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	650			V
Zero Gate Voltage Drain Current(Tc=25℃)	I <sub>DSS</sub>	V <sub>DS</sub> =650V,V <sub>GS</sub> =0V			1	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I <sub>DSS</sub>	V <sub>DS</sub> =650V,V <sub>GS</sub> =0V			100	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	$V_{GS}$ =±20V, $V_{DS}$ =0V			±200	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS}=V_{GS},I_{D}=250\mu A$	3	3.5	4	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =4A		460	530	mΩ
Dynamic Characteristics						
Input Capacitance	C <sub>lss</sub>	.,		532		pF
Output Capacitance	Coss	$V_{DS}$ =50V, $V_{GS}$ =0V,		21		pF
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1.0MHz		3.5		pF
Total Gate Charge	Qg			12.8		nC
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ =480 $V$ , $I_{D}$ =4 $A$ ,		1.9		nC
Gate-Drain Charge	$Q_{gd}$	V <sub>GS</sub> =10V		6		nC
Gate plateau voltage	Vgp			4.9		V
Intrinsic gate resistance	R <sub>G</sub>	f = 1 MHz open drain		35		Ω
Switching times			,			
Turn-on Delay Time	t <sub>d(on)</sub>			9		nS
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =480 $V$ , $I_D$ =4 $A$ ,		6		nS
Turn-Off Delay Time	$t_{d(off)}$	$R_G=1.7\Omega, V_{GS}=10V$		52		nS
Turn-Off Fall Time	t <sub>f</sub>			7		nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I <sub>SD</sub>	T 0500			8	Α
Pulsed Source-drain current(Body Diode)	I <sub>SDM</sub>	T <sub>C</sub> =25°C			24	Α
Forward On Voltage	V <sub>SD</sub>	Tj=25°C,I <sub>SD</sub> =8A,V <sub>GS</sub> =0V		0.9	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	T:-05°C ! 44		190		nS
Reverse Recovery Charge	Qrr	Tj=25°C,I <sub>F</sub> =4A,		1.34		uC
Peak Reverse Recovery Current	I <sub>rrm</sub>	di/dt=100A/µs		14		Α

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

<sup>2.</sup> Tj=25  $^{\circ}\text{C}$  ,VDD=50V,VG=10V, RG=25 $\Omega$ 



## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Safe operating area

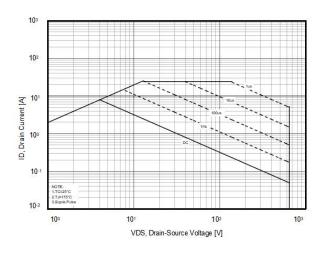


Figure 2. Capacitance

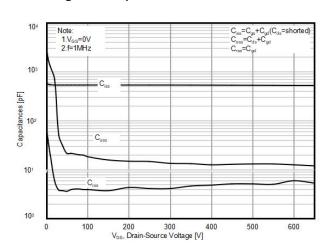


Figure 3. Transfer characteristics

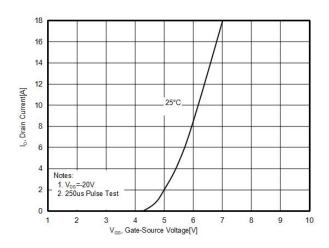


Figure 4. Output characteristics

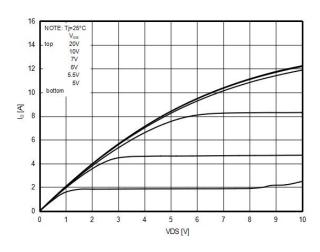


Figure 5. RDS(ON) vs Junction Temperature

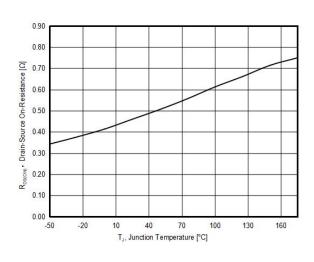


Figure 6. BV<sub>DSS</sub> vs Junction Temperature

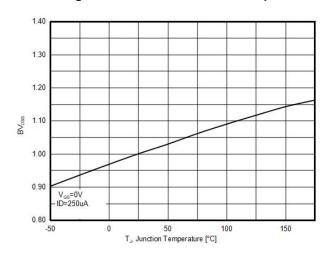




Figure 7. Maximum I<sub>D</sub> vs Junction Temperature

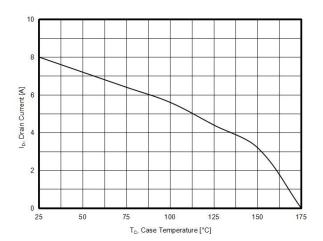


Figure 9. Static drain-source on resistance

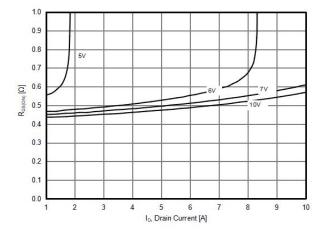


Figure 8. Gate charge waveforms

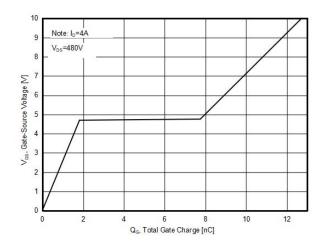
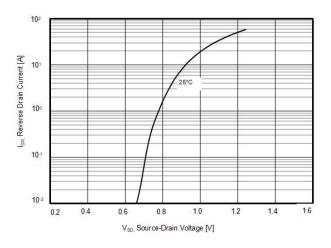


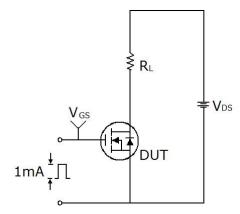
Figure 10. Source-Drain Diode Forward Voltag

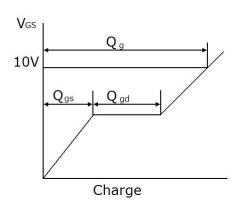




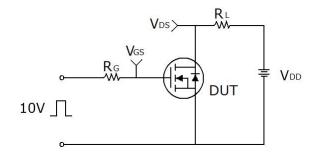
## **Test circuit**

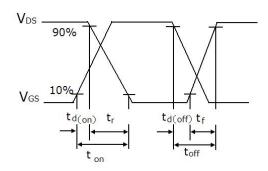
## 1) Gate charge test circuit & Waveform



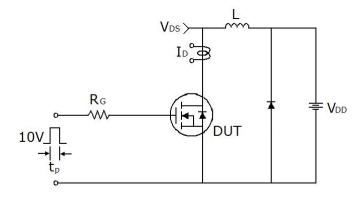


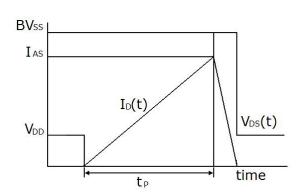
## 2) Switch Time Test Circuit:





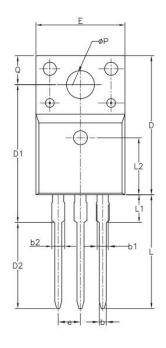
## 3) Unclamped Inductive Switching Test Circuit & Waveforms

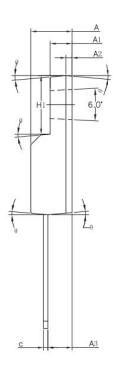






# **TO-220F-P Package Information**





Symbol	Dimensions In Millimeters		Dimension	s In Inches	
	Min.	Max.	Min.	Max.	
A	4.50	4.83	0.177	0.190	
A1	2.34	2.74	0.092	0.108	
A2	0.7	0 REF	0.028	REF	
A3	2.56	2.93	0.101	0.115	
b	0.70	0.90	0.028	0.035	
b1	1.18	1.38	0.046	0.054	
b2		1.47		0.058	
С	0.45	0.60	0.018	0.024	
D	15.67	16.07	0.616	0.631	
D1	15.55	15.95	0.611	0.627	
D2	9.60	10.00	0.377	0.393	
E	9.96	10.36	0.391	0.407	
е	2.5	54 BSC	0.100	BSC	
H1	6.48	6.88	0.255	0.270	
L	12.68	13.28	0.498	0.522	
L1		3.50		0.138	
L2	6.5	50 REF	0.255 REF		
Ø P	3.08	3.28	0.121	0.129	
Q	3.20	3.40	0.126	0.134	
θ1	1.0°	5.0°	1.00°	5.00°	



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